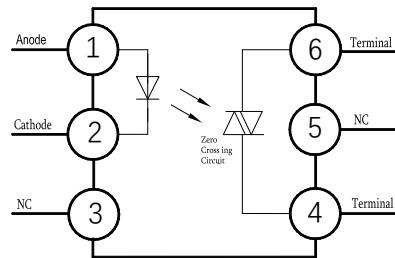


### Features

- Peak breakdown voltage:
- 250V: QX303X; 400V: QX304X; 600V: QX306X; 800V: QX308X
- High isolation voltage between input and output ( $V_{iso} = 5000V$  rms )
- Operating Temperature: -55°C~100°C

**HF**



### Applications

- Electromagnetic valve controls
- Light controls
- Static power switch
- AC Motor Drive
- Electromagnetic contact switch
- Solid state relay

### Mechanical Data

- Case: DIP-6L, DIP-6L(M),SMD-6L
- Molding Compound: UL Flammability Classification Rating 94V-0
- Terminals: Matte tin-plated leads; solderability-per MIL-STD-202, Method 208



## Ordering Information

BL    30VX    (M)    (G)    -    (U)    (N)    (Y)

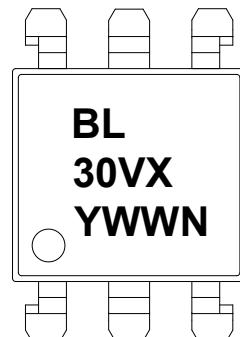
①      ②      ③      ④      ⑤      ⑥      ⑦

- ① Brand(BL)
- ② Product series(V:3,4,6,8;X:0,1,2,3)
- ③ Package type(DIP-6L:None, DIP-6L(M):M,SMD-6L:S)
- ④ Halogen option(None :Halogen free)
- ⑤ Lead frame (None: Copper)
- ⑥ Customer option 1 (0-9 or A-Z ornone)
- ⑦ Customer option 2 (0-9 or A-Z ornone)

Part Number	Package	Shipping Quantity	Marking Code
BL3031	DIP-6L	65 pcs / Tube	BL3031
BL3041M	DIP-6L(M)	65 pcs / Tube	BL3041
BL3061S	SMD-6L	1000 pcs / Tape & Reel	BL3061

## Marking Information

- "BL" denotes brand
- "V" denotes  $V_{DRM}$  digits: 3, 4, 6,8
- "X" denotes  $I_{FT}$  digits: 0, 1, 2, 3
- "Y" denotes Year : A(2024), B(2025), C(2026) .....
- "WW" denotes Week's number
- "N" denotes the day of Week



### Maximum Ratings (@ $T_A = 25^\circ\text{C}$ unless otherwise specified)

Parameter		Symbol	Value	Unit
Input	Forward Current	$I_F$	60	mA
	Reverse Voltage	$V_R$	6	V
	Power Dissipation	$P_D$	100	mW
	Derating factor (above $T_a = 85^\circ\text{C}$ )		3.8	$\text{mW}/^\circ\text{C}$
Output	Power Dissipation	$P_C$	300	mW
	Derating factor (above $T_a = 85^\circ\text{C}$ )		7.6	$\text{mW}/^\circ\text{C}$
	Off-state Output Terminal Voltage	$V_{DRM}$	250	V
			400	
			600	
			800	
	Peak repetitive surge current ( $pw=100\mu\text{s}, 120\text{pps}$ )	$I_{TSM}$	1	A
	Turn-on current (root mean square value)	$I_{T(RMS)}$	100	mA

### Thermal Characteristics

Parameter	Symbol	Value	Unit
Total Power Dissipation	$P_{TOT}$	330	mW
Isolation Voltage *1	$V_{ISO}$	5000	Vrms
Operating Temperature	$T_{OPR}$	-55 ~ +100	°C
Storage Temperature Range	$T_{STG}$	-55 ~ +125	°C
Soldering Temperature *2	$T_{SOL}$	260	°C

Notes:

1. 40 to 60% RH, AC for 1 minute. At this time, pins 1, 2 & 3 are shorted, and pins 4, 5 & 6 are shorted together.

2. For 10 seconds



Electrical Characteristics (@  $T_A = 25^\circ\text{C}$  unless otherwise specified)

Parameter		Symbol	Test Condition	Min.	Typ.	Max.	Unit
Input	Forward Voltage	$V_F$	$I_F=20\text{mA}$	-	1.36	1.5	V
	Reverse Leakage current	$I_R$	$V_R=6\text{V}$	-	-	10	$\mu\text{A}$
Output	Peak Blocking Current	BL303X	$I_{DRM}$ $V_{DRM}=\text{Rated } V_{DRM},$ $I_F=0\text{mA}$	-	-	100	nA
		BL304X		-	-	500	
		BL306X		-	-	-	V/ $\mu\text{s}$
		BL308X		-	-	-	
Transfer Characteristics	Peak on-state voltage		$V_{TM}$	$I_{TM}=100\text{mA},$ $I_F=\text{Rated } I_{FT}$	-	3	V
	Critical Rate of Rise off-state Voltage	BL303X	$dv/dt$ $V_{PEAK}=\text{Rated } V_{DRM},$ $I_F=0\text{mA}$	1000	-	-	V/ $\mu\text{s}$
		BL304X					
		BL306X					
		BL308X		600	-	-	
	Inhibition voltage (MT1-MT2 voltage above which device will not trigger)		$V_{inh}$	$I_F=\text{Rated } I_{FT}$	-	20	V
	Leakage in Inhibited State		$I_{DRM2}$	$I_F=\text{Rated } I_{FT}$ $V_{DRM}=\text{Rated } V_{DRM}$ off state	-	500	$\mu\text{A}$
Transfer Characteristics	LED trigger current	BL3031	$I_{FT}$  Main terminal voltage = 3V	-	-	15	mA
		BL3041		-	-	10	
		BL3061		-	-	5	
		BL3081		-	-	-	
		BL3032		-	-	-	
		BL3042		-	-	-	
		BL3062		-	-	-	
		BL3082		-	-	-	
		BL3033		-	-	-	
		BL3043		-	-	-	
		BL3063		-	-	-	
	Holding Current		$I_H$	-	250	-	$\mu\text{A}$

### Ratings and Characteristics Curves (@ $T_A = 25^\circ\text{C}$ unless otherwise specified)

Fig.1 LED Positive voltage vs Positive current

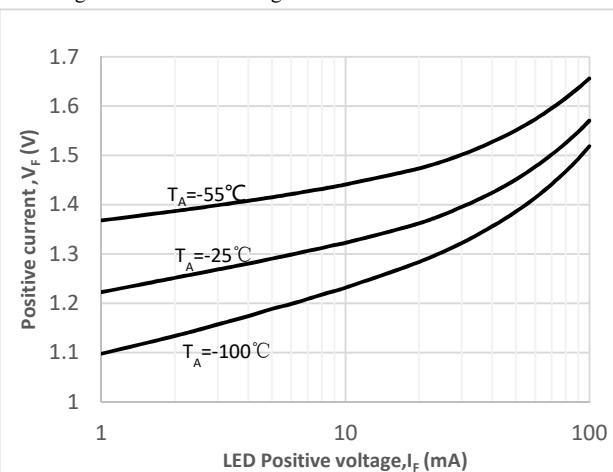


Fig.2 On-state characteristic

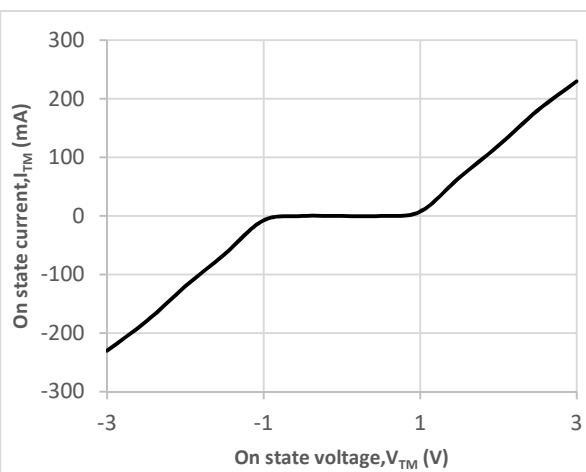


Fig.3 Trigger current vs Ambient temperature

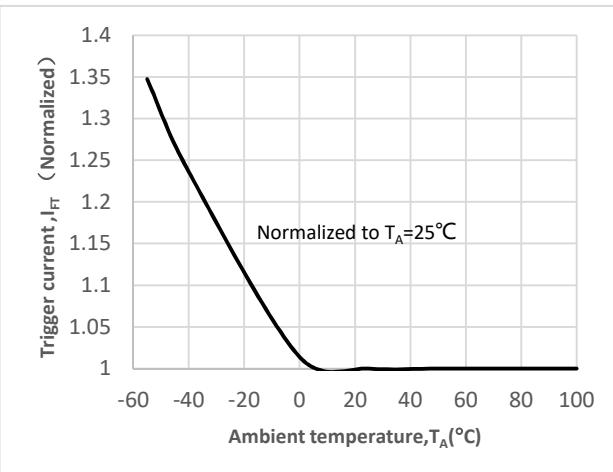


Fig.4 LED Trigger current vs LED Pulse Width

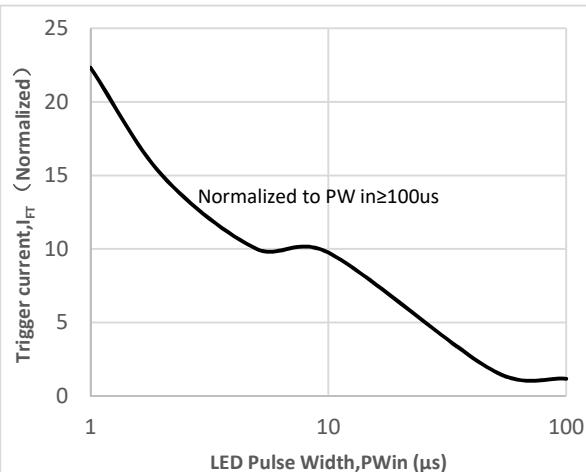


Fig.5 Holding current vs Temperature

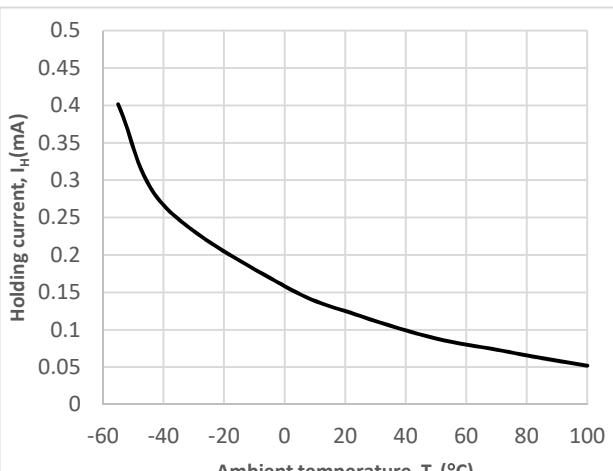


Fig.6 Leakage current vs Temperature

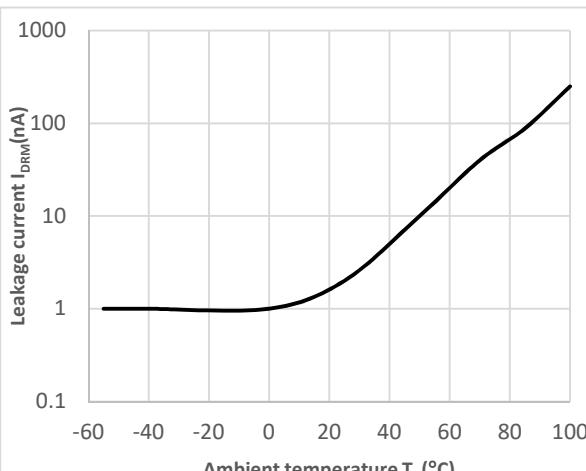




Fig.7 Inhibit state leakage current vs Ambient temperature

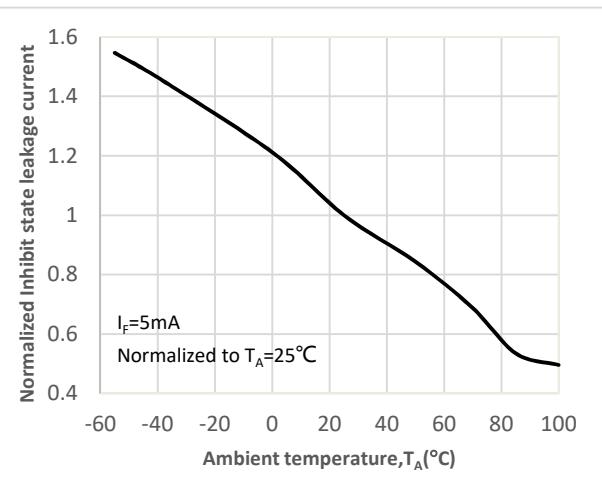


Fig.8 Inhibition voltage vs Ambient temperature

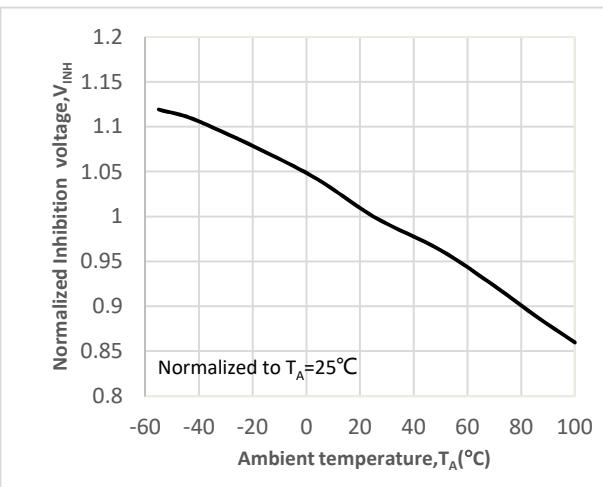
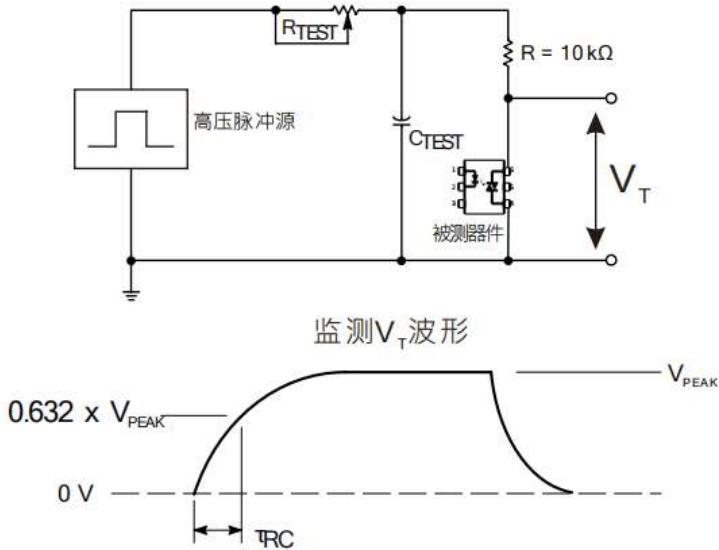


Fig.9 Static dv / dt test circuit and waveform



The high voltage pulse applied to the output of the device under test through the RC circuit is set to the required  $V_{PEAK}$  value. LED current is not applied. The waveform  $V_T$  is monitored with X100 probe. By adjusting the  $R_{TEST}$  value, the  $dv/dt$  (slope) increases until the device under test is observed to be triggered (waveform collapse). Then  $dv/dt$  drops until the device under test stops being triggered. At this point, RC is recorded and the  $dv/dt$  calculated.

$$dv/dt = \frac{0.632 \times V_{PEAK}}{\tau_{RC}}$$

For example,  $V_{PEAK} = 400V$  for QX302X series. The  $dv/dt$  value is calculated as follows:

$$dv/dt = \frac{0.632 \times 400}{\tau_{RC}} = \frac{252}{\tau_{RC}}$$



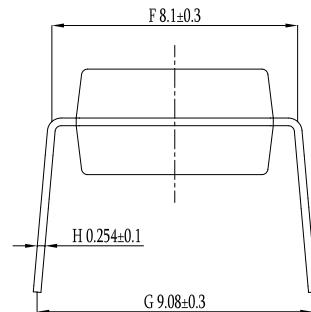
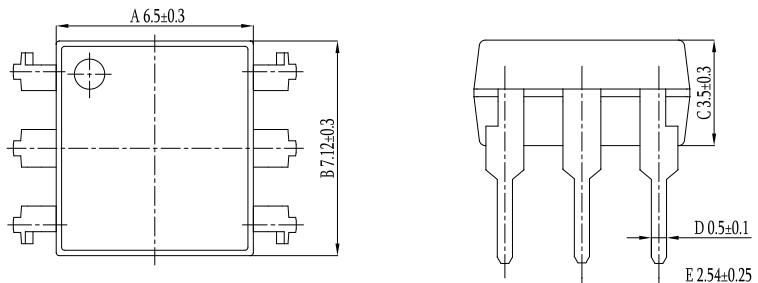
银河微电  
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# Zero Cross Triac Driver Photocouple

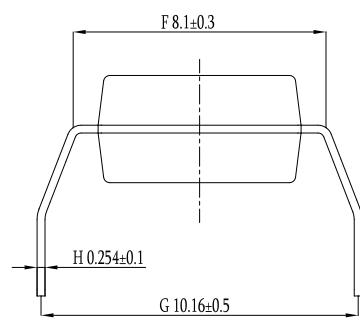
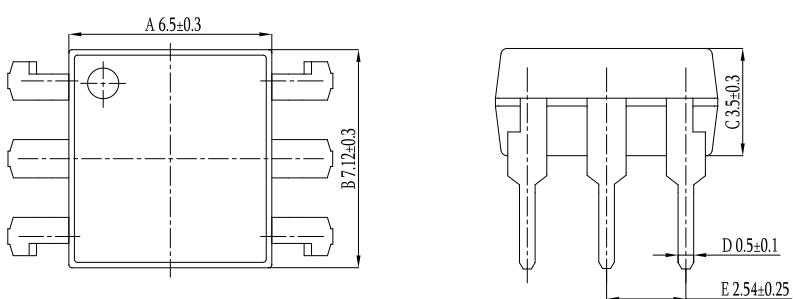
## BL303X ,BL304X,BL306X,BL308X

### Package Outline Dimensions (unit: mm)

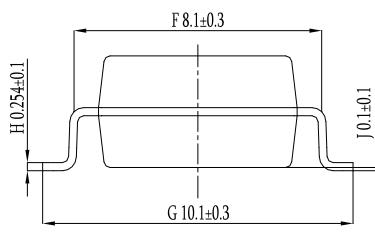
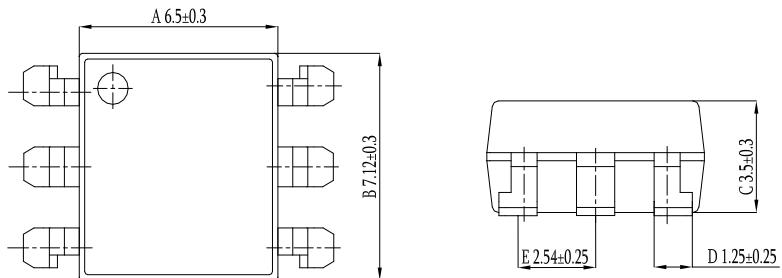
#### DIP-6L



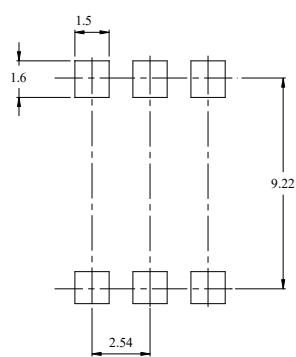
#### DIP-6L(M)



#### SMD-6L

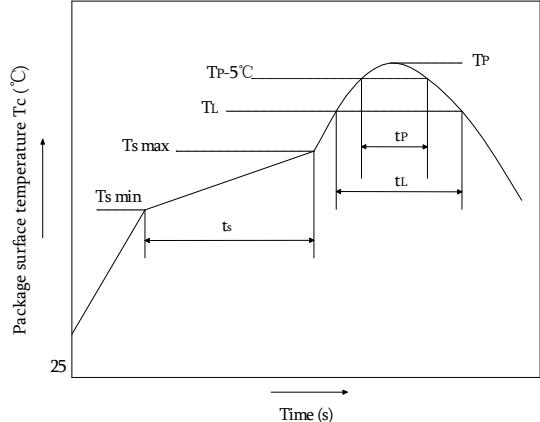


### SOLDERING FOOTPRINT (unit: mm)





## Reflow soldering

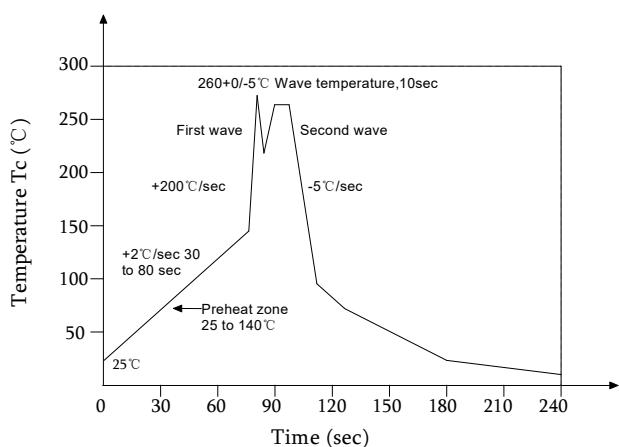


	Symbol	Min	Max	Unit
Preheat temperature	Ts	150	200	°C
Preheat time	ts	60	120	s
Ramp-up rate (TL to TP)			3	°C/s
Liquidus temperature	TL	217		°C
Time above TL	tL	60	150	s
Peak temperature	TP		260	°C
Time during which Tc is between (TP-5) and TP	tp		30	s
Ramp-down rate (TP to TL)			6	°C/s

### Note:

Reflow soldering is recommended at the temperatures and times shown, no more than three times.

## Wave soldering



Profile feature	
Average ramp-up rate	~200°C/s
Heating rate during preheat	1°C/s to 2°C/s typical; 4°C/s maximum
Final preheat temperature Ts	~130°C
Preheat time (25°C to Ts)	>60s
Peak temperature TP	260°C
Time within peak temperature tp	10s
Ramp-down rate	5°C/s maximum

### Soldering with hand soldering iron

- Hand soldering iron is only used for product rework or sample testing.
- Hand soldering iron requirements: Temperature: 360 °C + 5°C within 3s.



## Packing

Package Type	Packing Form	Quantity per Tube & Reel	Quantity per Box	Quantity per Carton	Antistatic Bag Specification	Box Specification	Carton Specification	Note
DIP-6L	Tube(500mm)	65 pcs/tube	25 tubes /box	12 boxes /ctn	190*670mm	520*105*50mm	545*372*235mm	Straight insert type material tube
DIP-6L(M)	Tube(500mm)	65 pcs/tube	25 tubes /box	12 boxes /ctn	190*670mm	520*105*50mm	545*372*235mm	Seagull foot (M foot) tube
SMD-6L	Reel( $\phi$ 330mm)	1000 pcs/reel	2 reels /box	5 boxes /ctn	380*420mm	350*340*60mm	365*330*370mm	Guard band 200mm /min.

### ■Summary table

#### ■ DIP-6L/ DIP-6L(M) (Tube)

Qty/ tube : 65 pcs. Qty/box: 1.625 pcs.

Qty/ctn : 19500 pcs.

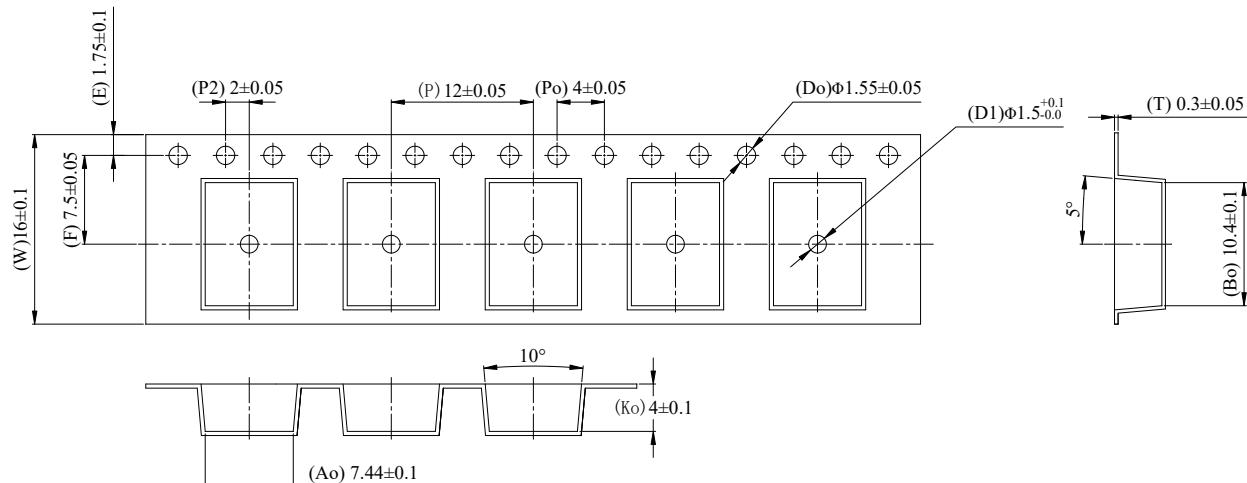
Schematic: (unit:mm)

#### ■SMD-6L (Reel)

Qty/reel: 1000 pcs. Qty/box: 2000 pcs.

Qty/ctn : 10000 pcs.

Schematic: (unit:mm)



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